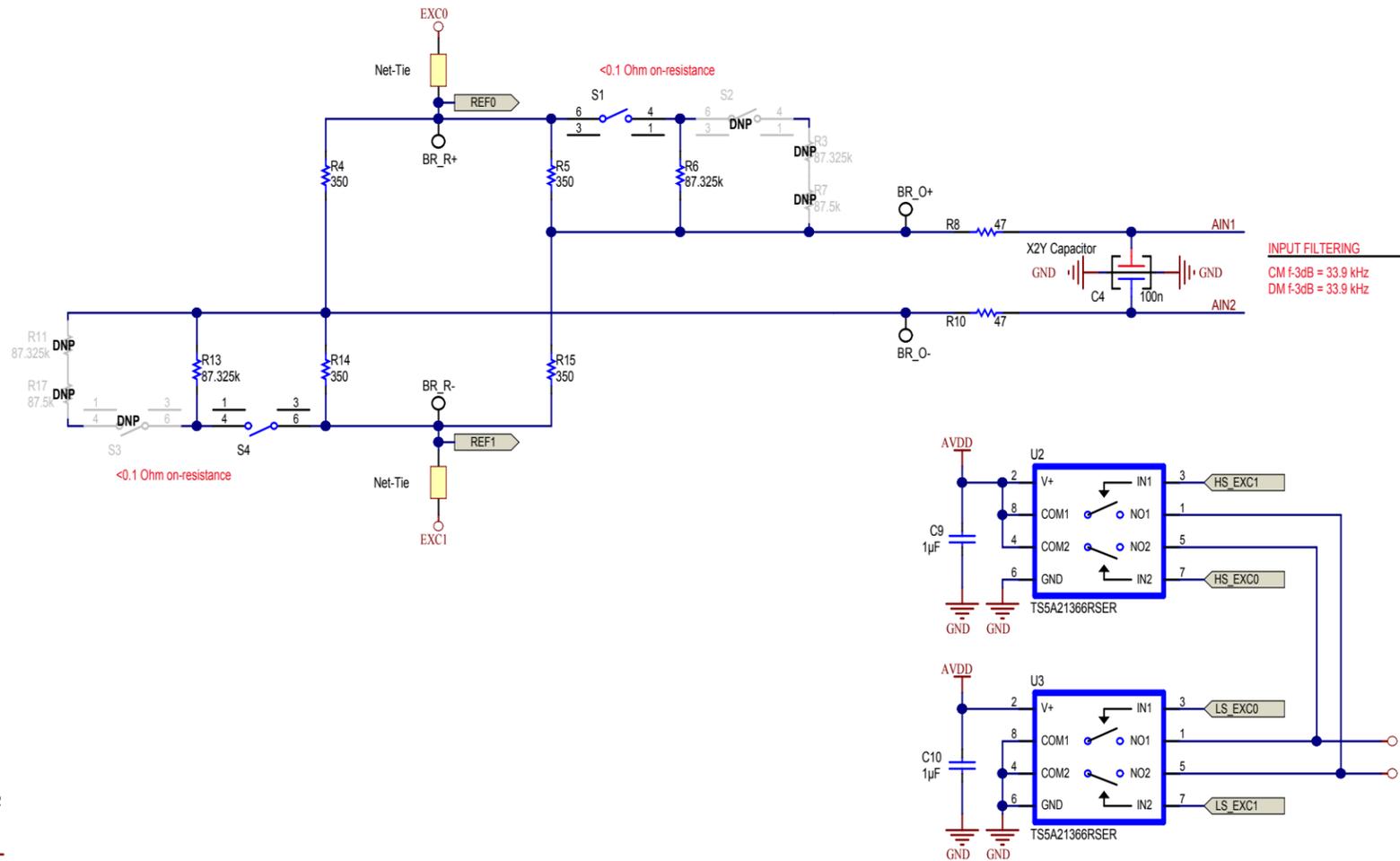
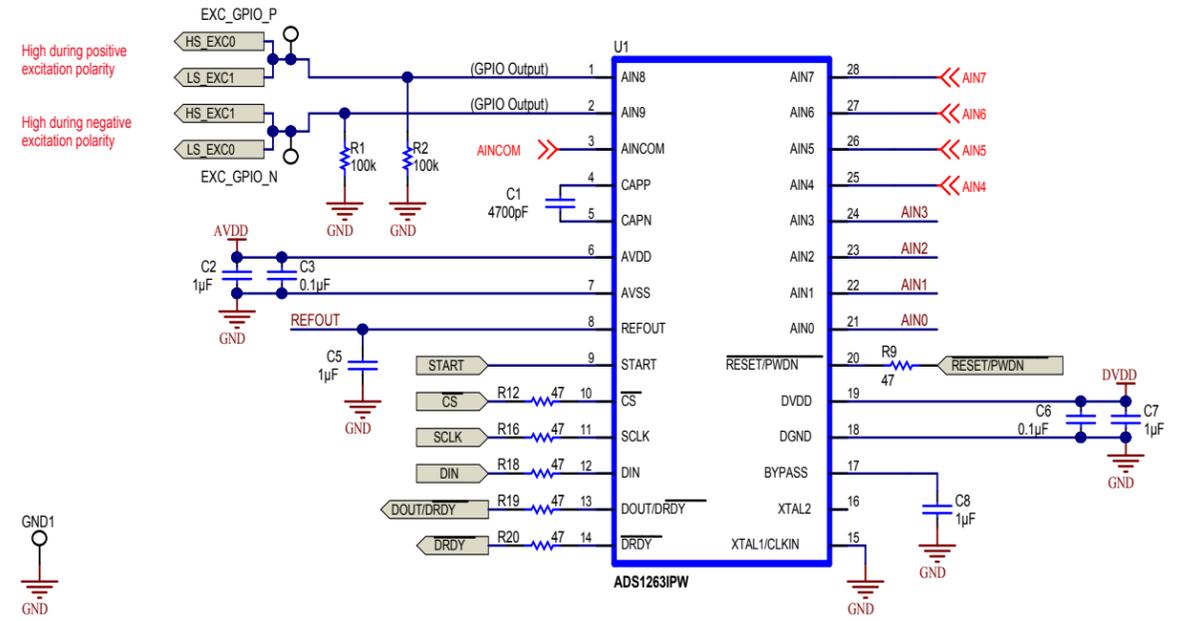


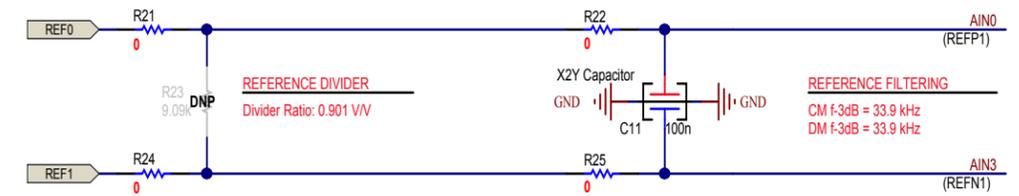
### Bridge Simulator and Excitation Switches



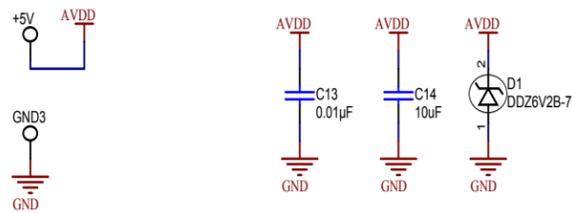
### Analog-to-Digital Converter (ADS1263)



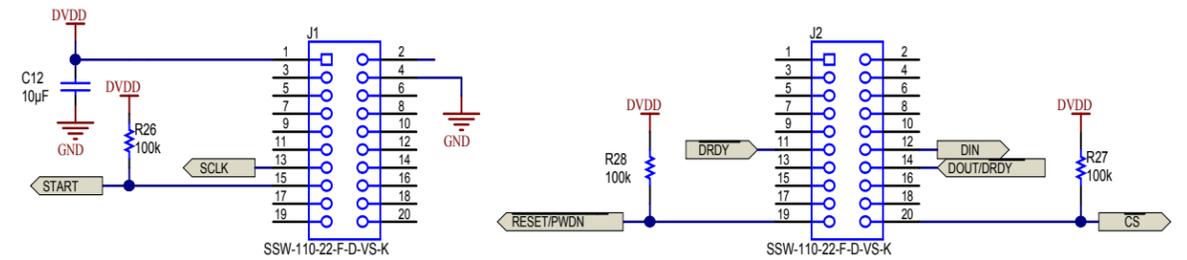
### Reference Divider and Filter



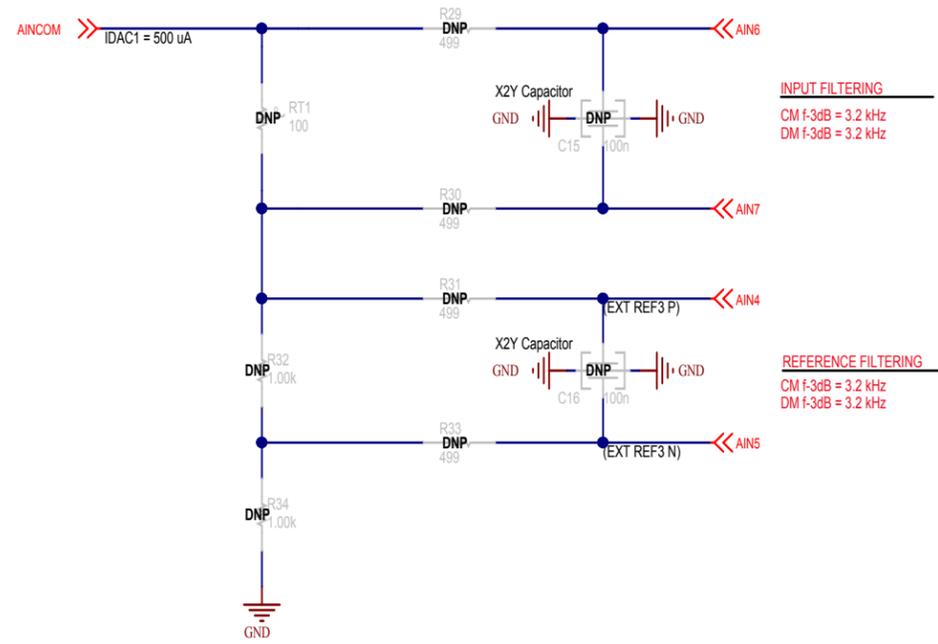
### Analog Supply (External Source)



### LaunchPad Connectors (MSP-EXP430F5529LP)



### Surface Mount Temperature Sensor (Not Used)



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Number:	TIPD188	Rev:	B	Designed for:	Public Release	Mod. Date:	7/10/2015
SVN Rev:	Version control disabled	Project Title:	TI Designs Precision	Sheet Title:	Schematic for TIPD188 (Not Used)		
Drawn By:	Christopher Hall	Assembly Variant:	002	File:	TIDU188 Temp Sensor.SchDoc	Sheet:	2 of 2
Engineer:	Christopher Hall	Contact:	http://e2e.ti.com/support/data_converters/	Size:	B		



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